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Clock Generator Selector Guide

Universal clock generators simplify traditional board designs by synthesizing frequencies from either a reference input clock or a common low-cost crystal, providing low-jitter output clocks. When used together with Microsemi clock distribution fanout buffers, the clock generators provide customers with improved board performance and complete timing solutions.

Any-Rate Clock Synthesis Devices

Product	Independent Output Freq. Families	Inputs	Crystal Input Freq. Range	Xtal Oscillator or CMOS Input Freq. Range	Diff Input Freq. Range	Low-Jitter APLLs	Typical Jitter fs RMS	NCO Mode	NCO ppb	Diff Outputs	CMOS Outputs	Output Freq. Range	NV Memory	Host Bus	Supply Voltage	Pkg Size, mm
ZL30236	2	1 XTAL	20 M, 24.576 M			2	700			8	4	1 k-750 M	OTP	SPI/I2C	3.3 + 1.8	11 x 11
ZL30237	2	1 XTAL	20 M, 24.576 M			2	700	•	0.24	8	4	1 k-750 M	OTP	SPI/I2C	3.3 + 1.8	11 x 11
ZL30230	4	1 XTAL	20 M, 24.576 M			2	700			4-12	4-12	1 k-750 M	OTP	SPI/I2C	3.3 + 1.8	11 x 11
MAX24405	2	1 XTAL/SE, 3 D/SE	25 M-52 M	9.72 M-160 M	9.72 M-750 M	2	180 ¹			0-5	0-10	<1 Hz-750 M	Ext EE	SPI	3.3 + 1.8	10 x 10
MAX24505	2	1 XTAL/SE, 3 D/SE	25 M-52 M	9.72 M-160 M	9.72 M-750 M	2	180 ¹			0-5	0-10	<1 Hz-750 M	Int EE	SPI	3.3 + 1.8	10 x 10
MAX24410	2	1 XTAL/SE, 3 D/SE	25 M-52 M	9.72 M-160 M	9.72 M-750 M	2	180 ¹			0-10	0-20	<1 Hz-750 M	Ext EE	SPI	3.3 + 1.8	10 x 10
MAX24510	2	1 XTAL/SE, 3 D/SE	25 M-52 M	9.72 M-160 M	9.72 M-750 M	2	180 ¹			0-10	0-20	<1 Hz-750 M	Int EE	SPI	3.3 + 1.8	10 x 10
ZL30250	1	1 XTAL/SE, 3 D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	1	160 ¹	•	0.01	0-3	0-6	<1 Hz-1035 M ²	Ext EE ³	SPI/I2C	3.3 + 1.8	5 x 5
ZL30251	1	1 XTAL/SE, 3 D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	1	160 ¹	•	0.01	0-3	0-6	<1 Hz-1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 x 5
ZL30244	2	2 XTAL/SE, 6 D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	2	160 ¹	•	0.01	0-6	0-12	<1 Hz-1035 M ²	Ext EE ³	SPI/I2C	3.3 + 1.8	5 x 10
ZL30245	2	2 XTAL/SE, 6 D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	2	160 ¹	•	0.01	0-6	0-12	<1 Hz-1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 x 10
ZL30260	2	1 XTAL/SE, 3D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	1	170 ¹	•	0.01	0-6	0-12	1 Hz-1035 M ²	Ext EE ⁴	SPI/I2C	Note ⁵	8 x 8
ZL30261	2	1 XTAL/SE, 3 D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	1	170 ¹	•	0.01	0-6	0-12	1 Hz-1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 x 8
ZL30262	2	1 XTAL/SE, 3 D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	1	170 ¹	•	0.01	0-10	0-20	1 Hz-1035 M ²	Ext EE ⁴	SPI/I2C	Note ⁵	8 x 8
ZL30263	2	1 XTAL/SE, 3 D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	1	170 ¹	•	0.01	0-10	0-20	1 Hz-1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 x 8
ZL30264	4	1 XTAL/SE, 3 D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	2	170 ¹	•	0.01	0-6	0-12	1 Hz-1035 M ²	Ext EE ⁴	SPI/I2C	Note ⁵	8 x 8
ZL30265	4	1 XTAL/SE, 3 D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	2	170 ¹	•	0.01	0-6	0-12	1 Hz-1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 x 8
ZL30266	4	1 XTAL/SE, 3 D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	2	170 ¹	•	0.01	0-10	0-20	1 Hz-1035 M ²	Ext EE ⁴	SPI/I2C	Note ⁵	8 x 8
ZL30267	4	1 XTAL/SE, 3 D/SE	25 M-60 M	9.72 M-300 M	9.72 M-1250 M	2	170 ¹	•	0.01	0-10	0-20	1 Hz-1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 x 8

Abbreviation Key: D = differential
Int EE = internal EEPROM
3 = up to four configurations (pin-selectable)

SE = single-ended (CMOS)
OTP = one-time programmable
4 = up to eight configurations (pin-selectable)

NCO = numerically controlled oscillator
1 = integer-mode APLL-only operation
5 = 2.5 V only, 3.3 V only, 1.8 V + 2.5 V, 1.8 V + 3.3 V
Ext EE = external EEPROM
2 = spread spectrum-capable

Clock Generator Selector Guide

Rate Conversion/Jitter Attenuation Devices

Product	Independent Output Freq. Families	Inputs	Crystal Input Freq. Range	Xtal Oscillator or CMOS Input Freq. Range	Diff Input Freq. Range	Low-Jitter APLLs	Typical Jitter fs RMS	DPLL Features: Ref. Switching/ Holdover/ DPLL Bandwidth	NCO Mode	NCO ppb	Diff Outputs	CMOS Outputs	Output Freq. Range	NV Memory	Host Bus	Supply Voltage	Pkg Size, mm
MAX24605	2	1 XTAL/SE, 3 D/SE	25 M–52 M	2 kHz–160 M	2 kHz–750 M	2	180 ¹	Glitchless/ Digital Hold/ 4 Hz–400 Hz	•	<0.001	0–5	0–10	<1 Hz–750 M	Ext EE	SPI	3.3 + 1.8	10 × 10
MAX24610	2	1 XTAL/SE, 3 D/SE	25 M–52 M	2 kHz–160 M	2 kHz–750 M	2	180 ¹	Glitchless/ Digital Hold/ 4 Hz–400 Hz	•	<0.001	0–10	0–20	<1 Hz–750 M	Ext EE	SPI	3.3 + 1.8	10 × 10
ZL30159	1	1 XTAL, 1 D	20 M or 24.578 M	1 Hz–177.5 M	1 Hz–750 M	1	<1000				0	2	1 Hz–177.5 M		SPI/I2C	3.3 + 1.8	9 × 9
ZL30252	1	1 XTAL/SE, 3 D/SE	25 M–60 M	1 kHz–300 M	1 kHz–1250 M	1	160 ¹	Glitchless/ Digital Hold/ 14 Hz–500 Hz	•	0.01	0–3	0–6	<1 Hz–1035 M ²	Ext EE ³	SPI/I2C	3.3 + 1.8	5 × 5
ZL30253	1	1 XTAL/SE, 3 D/SE	25 M–60 M	1 kHz–300 M	1 kHz–1250 M	1	160 ¹	Glitchless/ Digital Hold/ 14 Hz–500 Hz	•	0.01	0–3	0–6	<1 Hz–1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 × 5
ZL30254	1	1 XTAL, 2 SE	49.152 MHz	8 kHz or 25 MHz		1	<1 ps	Glitchless/ Digital Hold/ 25 Hz			2	0	125 MHz or 156.25 MHz		None	3.3 + 1.8	5 × 5
ZL30255	2	2 XTAL/SE, 6 D/SE	25 M–60 M	1 kHz–300 M	1 kHz–1250 M	2	160 ¹	Glitchless/ Digital Hold/ 14 Hz–500 Hz	•	0.01	0–6	0–12	<1 Hz–1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 × 10

Abbreviation Key: D = differential
 Ext EE = external EEPROM
 1 = integer-mode APLL-only operation

SE = single-ended (CMOS)
 Int EE = internal EEPROM
 2 = spread spectrum-capable

NCO = numerically controlled oscillator
 OTP = one-time programmable
 3 = up to four configurations pin-selectable



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